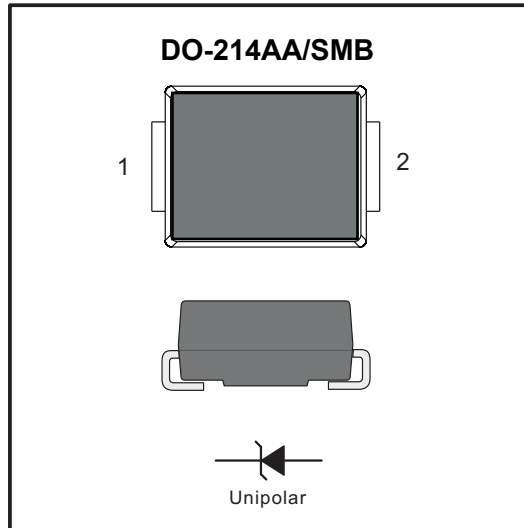


### PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



### Features

- ◆ Metal silicon junction, majority carrier conduction
- ◆ For surface mounted applications
- ◆ Low power loss, high efficiency
- ◆ High forward surge current capability
- ◆ For use in low voltage, high frequency inverters , free wheeling, and polarity protection applications

### MECHANICAL DATA

- ◆ Case: SMB
- ◆ Terminals: Solderable per MIL-STD-750, Method 2026
- ◆ Approx. Weight: 60mg / 0.0021oz

### Absolute Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

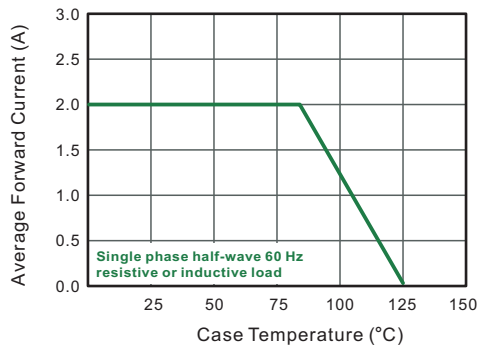
Parameter	Symbols	SS22	SS24	SS26	SS28	SS210	SS212	SS2150	SS220	Units
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	20	40	60	80	100	120	150	200	V
Maximum RMS voltage	$V_{RMS}$	14	28	42	56	70	84	105	140	V
Maximum DC Blocking Voltage	$V_{DC}$	20	40	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	2.0								A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	$I_{FSM}$	55				45				A
Max Instantaneous Forward Voltage at 2 A	$V_F$	0.55		0.70		0.85		0.95		V
Maximum DC Reverse Current $T_a = 25^\circ\text{C}$ at Rated DC Reverse Voltage $T_a = 100^\circ\text{C}$	$I_R$	0.5 5			0.3 3				mA	
Typical Junction Capacitance <sup>(1)</sup>	$C_j$	220				110				pF
Typical Thermal Resistance <sup>(2)</sup>	$R_{\theta JA}$	60								°C/W
Operating Junction Temperature Range	$T_j$	-55 ~ +125								°C
Storage Temperature Range	$T_{stg}$	-55 ~ +150								°C

( 1 ) Measured at 1 MHz and applied reverse voltage of 4 V D.C

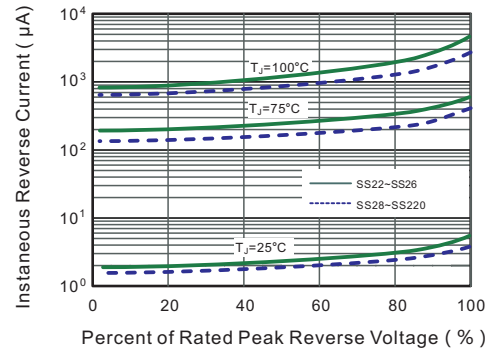
( 2 ) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

## Typical Characteristics

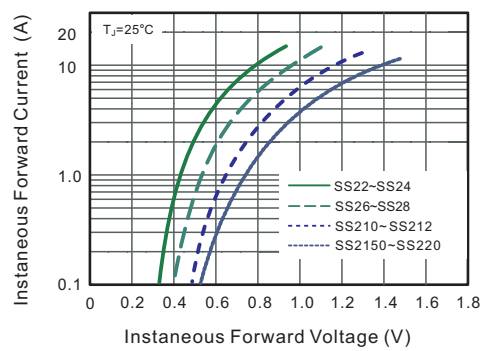
**Fig.1 Forward Current Derating Curve**



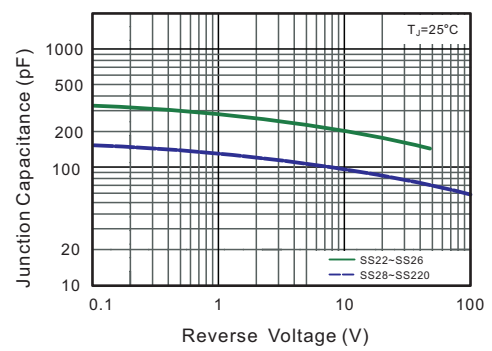
**Fig.2 Typical Reverse Characteristics**



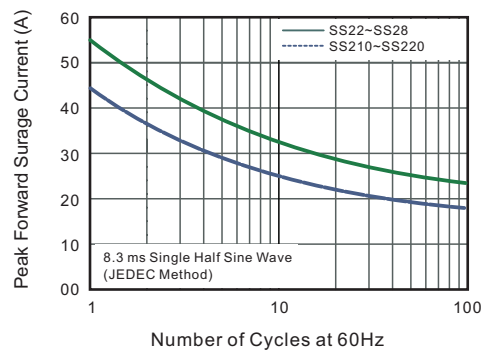
**Fig.3 Typical Forward Characteristic**



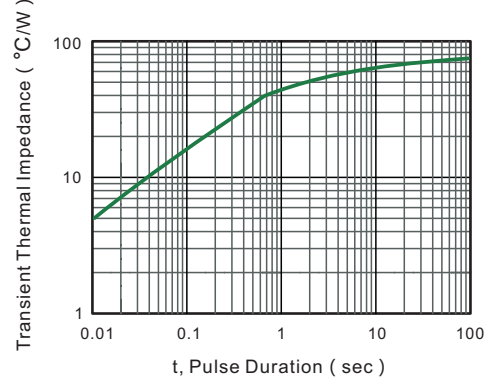
**Fig.4 Typical Junction Capacitance**



**Fig.5 Maximum Non-Repetitive Peak Forward Surge Current**



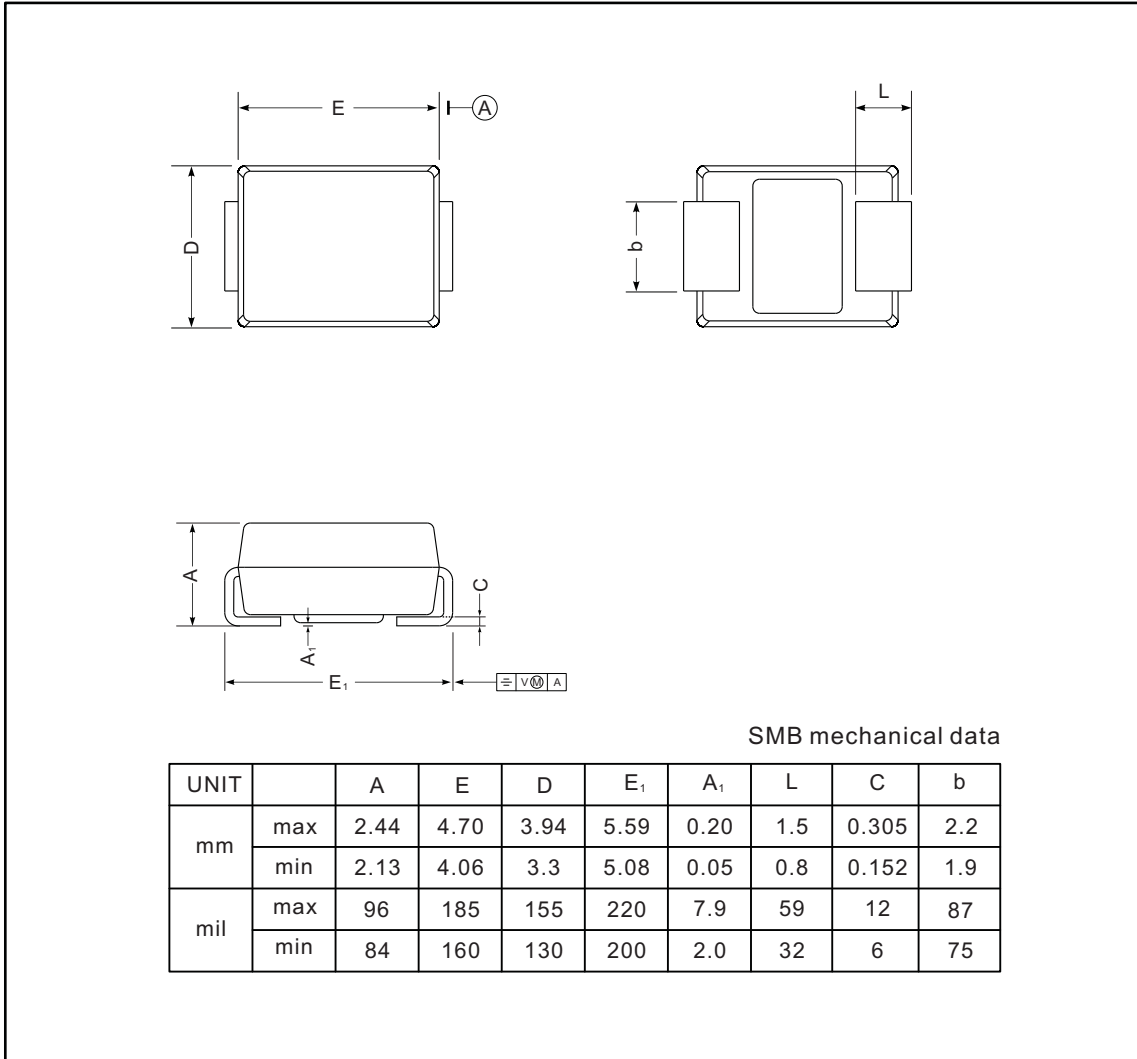
**Fig.6- Typical Transient Thermal Impedance**



### PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SMB



### The recommended mounting pad size

